### Silicon Carbide Device Update

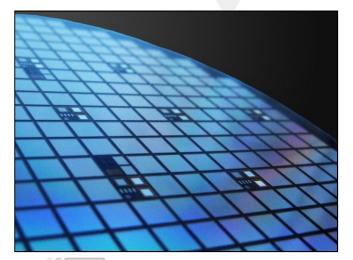
#### **David Sheridan**

**VP Technology Development** 

#### High Megawatt Power Conditioning System Workshop

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| Material property    | Si           | 4H-SiC      | GaN         |
|----------------------|--------------|-------------|-------------|
| Bandgap              | 1.12 eV      | 3.25 eV     | 3.4 eV      |
| Breakdown field      | 0.25 MV/cm   | ~3 MV/cm    | ~3 MV/cm    |
| Thermal conductivity | 1.5 W/cm•K   | 4.9 W/cm∙K  | 1.3 W/cm•K  |
| Electron mobility    | 1200 cm²/V•s | 800 cm²/V•s | 900 cm²/V•s |
| Dielectric constant  | 11.7         | 9.7         | 9           |

- Silicon carbide is an ideal power semiconductor material
- Most mature "wide bandgap" power semiconductor material
- Electrical breakdown strength ~ 10X higher than Si
- Commercial substrates available since 1991 –
- ✓ now at 100 mm dia; 150 mm dia soon
- Defects up to 1,000 times less than GaN
- <u>Thermal conductivity ~ 3X greater than Si or GaN</u>





### SemiSouth — SiC Power Semi Technology Leader

 $\rightarrow$  1200 V – 1700 V Trench "normally – off" JFETs  $\rightarrow$  650 V, 1200V – 1700 V Trench "normally – on" JFETs  $\rightarrow$  1200 V Schottky Diodes

SemiSouth silicon carbide trench technology offers higher efficiency, greater power density & higher reliability than comparable silicon-based devices



Servers

Wind

SiC Wafer



## SemiSouth SemiSouth VJFET Technology

### Why the SiC Trench JFET?

a Cost

a 3-10 X smaller die size

Up to 50% fewer manufacturing steps

#### Performance

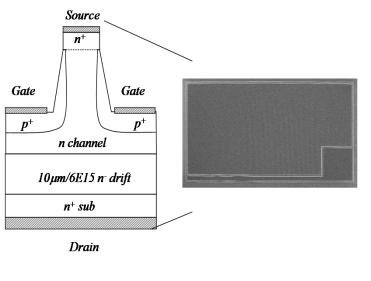
**5-10X lower** switching energies
 **Normally-on or off** (industry first and only)
 Enables high-frequency <u>and</u> high-efficiency
 Industry best on-resistance per unit area

#### Reliability

Rugged structure for SiC JFET switch

- Over 1,000 hour HTRB
- No known degradation issues
- Robust operating range

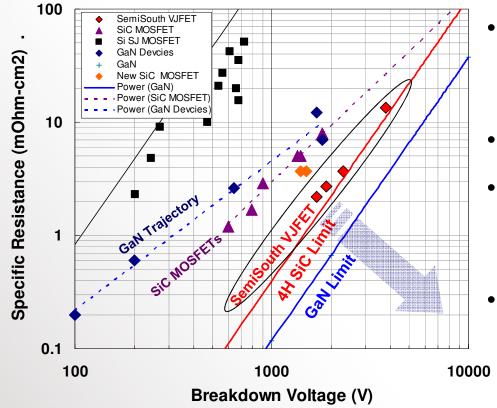
### SemiSouth Vertical-Channel JFET\*



- (+) Few mask layers
- (+) Low RPT
- (+)  $\mathbf{R}_{(on)sp} \approx 2-3 \text{ m}\Omega^* \text{cm}^2$

## SemiSouth Industry Leading Performance

Proprietary Compact design leads to ultra-low specific on-resistance in power JFET (normally-on or normally-off versions available)



- SemiSouth first and only to offer TRENCH SiC JFET beginning in 2008
- Near theoretical specific R<sub>DSON</sub>
- Normally-OFF <u>OR</u> Normally-ON use same device structure & manufacturing steps
- High reliability



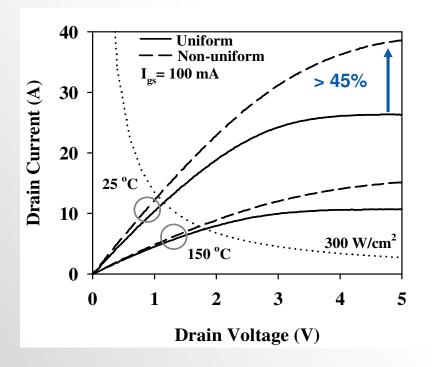
SemiSouth Advanced JFET Concepts

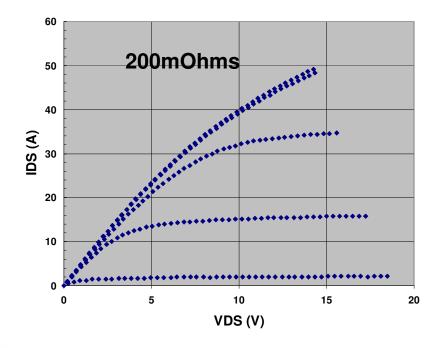
### High Current Normally-Off

- Demonstrated novel channel design for ٠ improved saturation current
- Significant increase in current and increased threshold range

### 3.3kV Design Normally-Off

- Normally-off SiC JFET 3.8kV Design ٠ (edge termination limited)
- Exceptionally low Rds(on) = 200mOhms > 50A saturation current

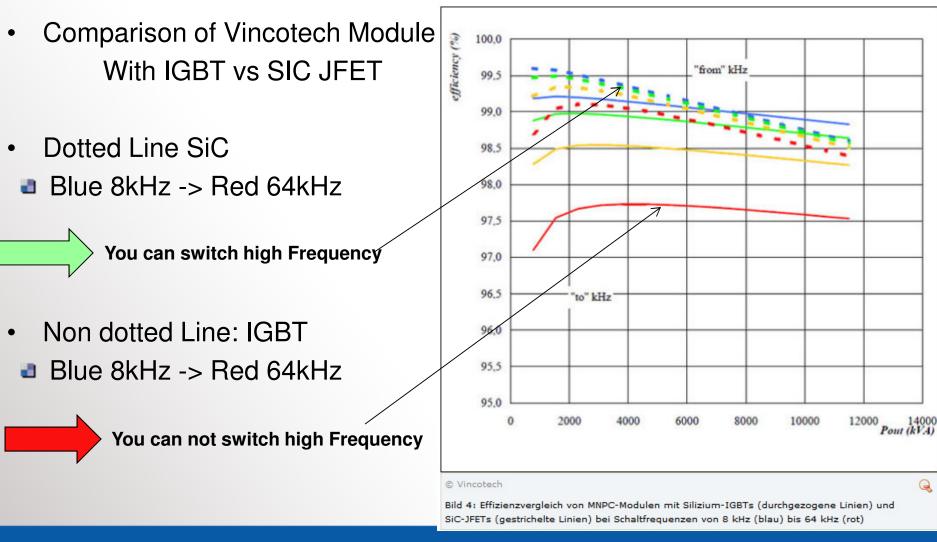




SIC UPDATE



### SemiSouth Comparison IGBT vs SiC



SIC UPDATE

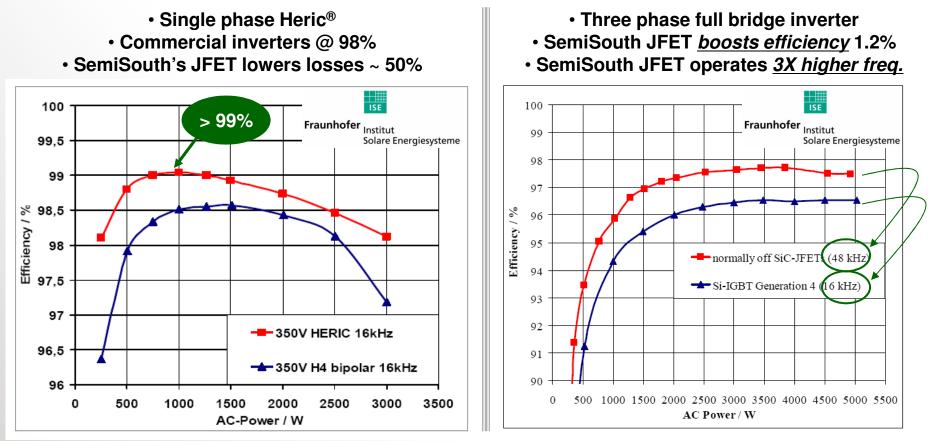
#### JFETs gegen IGBTs

7



### **Performance Validation** WORLD RECORD Power Conversion Efficiency\*

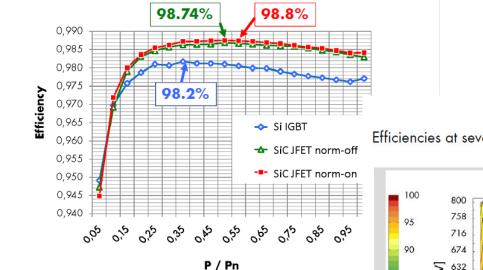
"We now use junction field-effect transistors (JFETs) made of silicon carbide (SiC) manufactured by SemiSouth Laboratories Inc.. This is the main reason for the improvement", - Prof. Bruno Burger, leader of the Power Electronics Group at Fraunhofer ISE, July 2009 press release.



\* Bruno Burger, Dirk Kranzer, "Extreme High Efficiency PV-Power Converters," EPE, Barcelona, Spain, 8-10

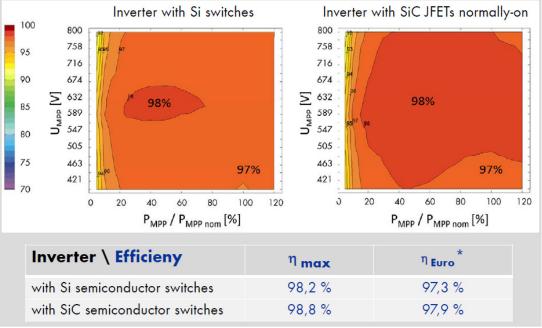
September 2009 SiC UPDATE

# SemiSouth SMA SiC JFET Inverter



Efficiencies at several DC link voltages (400V up to 800V) - "Photon test"





\* European Efficiency - specific weighted average value

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Dr. Regine Mallwitz, SMA: SiC & GaN User Forum, Birmingham 2011

SIC UPDATE

### 1. Technical benefit of SiC semiconductors

SemiSouth SMA Quote about SiC



SiC devices promise

- low switching losses
- high rated voltages
- high operating temperature
- high radiation hardness

#### For PV inverters this properties offer possibilities toward

- improved effiency above 99% (at same switching frequency like today)
- higher switching frequencies (at same level of losses like today)
- higher level of output power (at same switching frequency and losses)
- higher DC input voltages

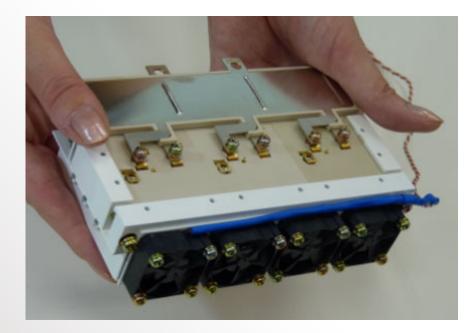
- ightarrow reduction of cooling effort ightarrow system size
- ightarrow reduction of system size ightarrow system costs
- → reduction of specific cost (per W)

Dr. Regine Mallwitz, SMA: SiC & GaN User Forum, Birmingham 2011





# SemiSouth Automotive prototype inverter





Sato, et al, International Conf. on SiC and Related Materials, Sept 2011

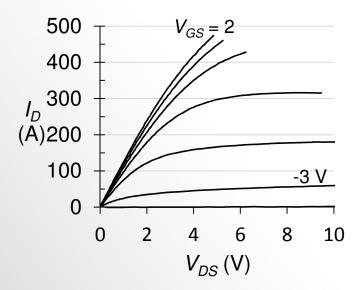
- Future Power Electronics Technology (FUPET) has developed an all-SiCdevice-based three-phase inverter with a 0.5-liter volume, verified to achieve an output power density of <u>30kWh/I</u>.
  "We believe this is the world's highest output power density for a smallvolume inverter," commented FUPET officials.
- Using SiC junction field-effect transistor (JFET) devices procured from SemiSouth Laboratories, the power modules operate up to 200 ℃.
- 500cc inverter connected to a threephase motor achieved <u>15kW output</u>, which is 30kW/l or 30W/cc. At 15kW output, conversion efficiency was <u>99%</u>.

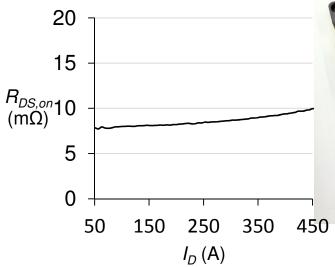


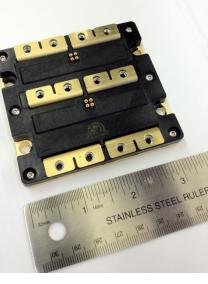
### SiC JFET power module



### Only 36 mm<sup>2</sup> of JFET die area per switch position (4 x SJDC120R045)







| Switching energies at 25 $^{\circ}$ C of SiC VJFET modules (I <sub>D</sub> = 100 A) and a Si IGBT module (I <sub>C</sub> = 150 A) |                |                 |                        |  |
|---|----------------|-----------------|------------------------|--|
|   | Turn-on energy | Turn-off energy | Total switching losses |  |
| Enhancement-mode SiC VJFET  | 0.72 mJ        | 0.46 mJ         | 1.18 mJ                |  |
| Depletion-mode SiC VJFET  | 0.33 mJ        | 0.90 mJ         | 1.23 mJ                |  |
| Si IGBT (Infineon)  | 8.5 mJ         | 8.5 mJ          | 17.0 mJ                |  |



# SemiSouth



- □ SiC trench JFET production since 2008
- Size and weight reduction are key elements to fight increasing faw material cost
- High frequency (power density) with improved efficiency is key to reducing weight and cost

### → HV SiC devices are possible, and scaling to higher currents

- □ What devices are needed for MV HV applications?
- □ Initial insertion applications?
- Device requirements?
- □ Cost targets?

